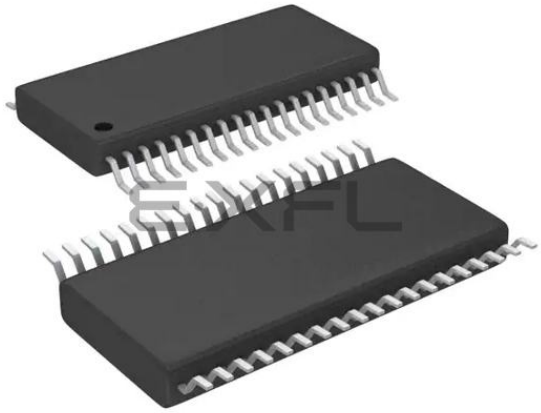

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	86MHz
Connectivity	SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	19
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc8661friabfxuma1

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XC866

8-Bit Single-Chip Microcontroller

Microcontrollers

Never stop thinking

2.4 Pin Definitions and Functions

Table 3 Pin Definitions and Functions

Symbol	Pin Number	Type	Reset State	Function
P0		I/O		**Port 0** Port 0 is a 6-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC.
P0.0	12		Hi-Z	TCK_0 JTAG Clock Input T12HR_1 CCU6 Timer 12 Hardware Run Input CC61_1 Input/Output of Capture/Compare channel 1 CLKOUT Clock Output RXDO_1 UART Transmit Data Output
P0.1	14		Hi-Z	TDI_0 JTAG Serial Data Input T13HR_1 CCU6 Timer 13 Hardware Run Input RXD_1 UART Receive Data Input COUT61_1 Output of Capture/Compare channel 1 EXF2_1 Timer 2 External Flag Output
P0.2	13		PU	$\overline{\text{CTRAP}}$_2 CCU6 Trap Input TDO_0 JTAG Serial Data Output TXD_1 UART Transmit Data Output/ Clock Output
P0.3	2		Hi-Z	SCK_1 SSC Clock Input/Output COUT63_1 Output of Capture/Compare channel 3
P0.4	3		Hi-Z	MTSR_1 SSC Master Transmit Output/ Slave Receive Input CC62_1 Input/Output of Capture/Compare channel 2
P0.5	4		Hi-Z	MRST_1 SSC Master Receive Input/ Slave Transmit Output EXINT0_0 External Interrupt Input 0 COUT62_1 Output of Capture/Compare channel 2

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$B2_H$	**PORT_PAGE** **Reset: 00_H** Page Register for PORT	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
80_H	**P0_DATA** **Reset: 00_H** P0 Data Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rwh	rwh	rwh	rwh	rwh	rwh
86_H	**P0_DIR** **Reset: 00_H** P0 Direction Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_DATA** **Reset: 00_H** P1 Data Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rwh	rwh	rwh	r			rwh	rwh
91_H	**P1_DIR** **Reset: 00_H** P1 Direction Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$A0_H$	**P2_DATA** **Reset: 00_H** P2 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
$A1_H$	**P2_DIR** **Reset: 00_H** P2 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_DATA** **Reset: 00_H** P3 Data Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
$B1_H$	**P3_DIR** **Reset: 00_H** P3 Direction Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 1										
80_H	**P0_PUDSEL** **Reset: FF_H** P0 Pull-Up/Pull-Down Select Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
86_H	**P0_PUDEN** **Reset: $C4_H$** P0 Pull-Up/Pull-Down Enable Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_PUDSEL** **Reset: FF_H** P1 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
91_H	**P1_PUDEN** **Reset: FF_H** P1 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$A0_H$	**P2_PUDSEL** **Reset: FF_H** P2 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$A1_H$	**P2_PUDEN** **Reset: 00_H** P2 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B0_H$	**P3_PUDSEL** **Reset: BF_H** P3 Pull-Up/Pull-Down Select Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
$B1_H$	**P3_PUDEN** **Reset: 40_H** P3 Pull-Up/Pull-Down Enable Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 2										
80_H	**P0_ALTSEL0** **Reset: 00_H** P0 Alternate Select 0 Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
86_H	**P0_ALTSEL1** **Reset: 00_H** P0 Alternate Select 1 Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_ALTSEL0** **Reset: 00_H** P1 Alternate Select 0 Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
91_H	**P1_ALTSEL1** **Reset: 00_H** P1 Alternate Select 1 Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$B0_H$	**P3_ALTSEL0** **Reset: 00_H** P3 Alternate Select 0 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

3.3.2 Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. Hence, it is possible to program the same WL, for example, with 16 bytes of data in two times (see **Figure 12**).

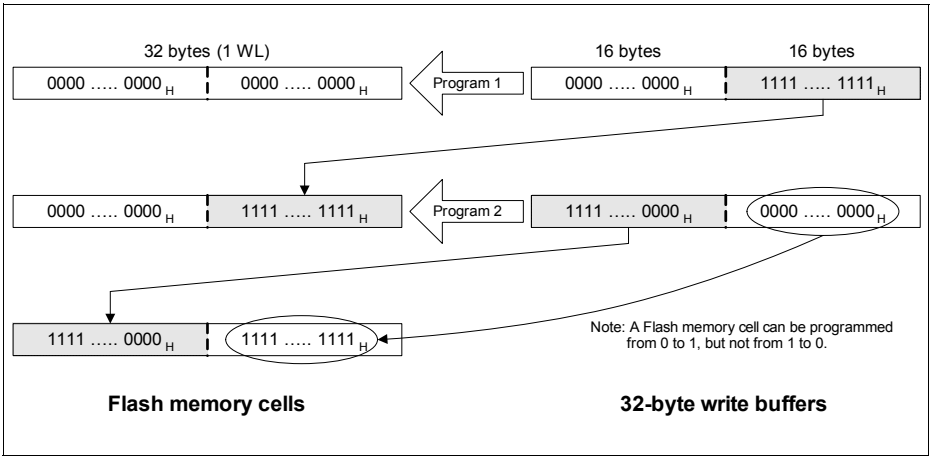


Figure 12 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent “over-programming”.

3.4.3 Interrupt Priority

Each interrupt source, except for NMI, can be individually programmed to one of the four possible priority levels. The NMI has the highest priority and supersedes all other interrupts. Two pairs of interrupt priority registers (IP and IPH, IP1 and IPH1) are available to program the priority level of each non-NMI interrupt vector.

A low-priority interrupt can be interrupted by a high-priority interrupt, but not by another interrupt of the same or lower priority. Further, an interrupt of the highest priority cannot be interrupted by any other interrupt source.

If two or more requests of different priority levels are received simultaneously, the request of the highest priority is serviced first. If requests of the same priority are received simultaneously, then an internal polling sequence determines which request is serviced first. Thus, within each priority level, there is a second priority structure determined by the polling sequence shown in **Table 18**.

Table 18 Priority Structure within Interrupt Level

Source	Level
Non-Maskable Interrupt (NMI)	(highest)
External Interrupt 0	1
Timer 0 Interrupt	2
External Interrupt 1	3
Timer 1 Interrupt	4
UART Interrupt	5
Timer 2, Fractional Divider, LIN Interrupts	6
ADC Interrupt	7
SSC Interrupt	8
External Interrupt 2	9
External Interrupt [6:3]	10
CCU6 Interrupt Node Pointer 0	11
CCU6 Interrupt Node Pointer 1	12
CCU6 Interrupt Node Pointer 2	13
CCU6 Interrupt Node Pointer 3	14

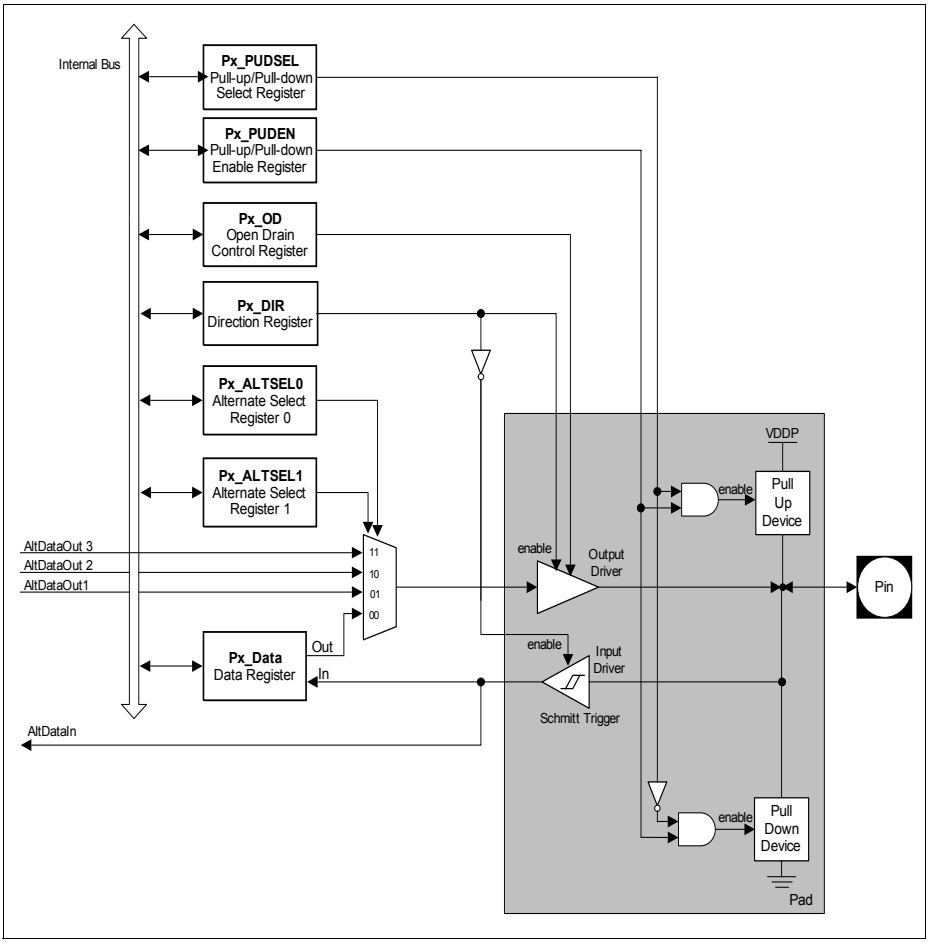


Figure 18 General Structure of Bidirectional Port

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert WDTTO) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDTRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2^8). The time period for an overflow of the WDT is programmable in two ways:

- the input frequency to the WDT can be selected to be either $f_{PCLK}/2$ or $f_{PCLK}/128$
- the reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}}$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see **Figure 28**. This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB should not be smaller than WDTREL.

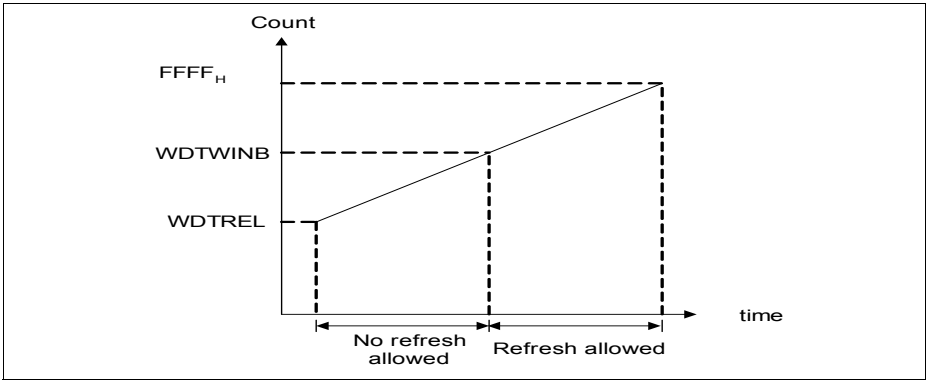


Figure 28 WDT Timing Diagram

Table 24 lists the possible watchdog time range that can be achieved for different module clock frequencies . Some numbers are rounded to 3 significant digits.

Table 24 Watchdog Time Ranges

Reload value in WDTREL	Prescaler for f_{PCLK}	
	2 (WDTIN = 0)	**128 (WDTIN = 1)**
	26.7 MHz	**26.7 MHz**
FF_H	19.2 µs	1.23 ms
$7F_H$	2.48 ms	159 ms
00_H	4.92 ms	315 ms

3.14 High-Speed Synchronous Serial Interface

The High-Speed Synchronous Serial Interface (SSC) supports full-duplex and half-duplex synchronous communication. The serial clock signal can be generated by the SSC internally (master mode), using its own 16-bit baud-rate generator, or can be received from an external master (slave mode). Data width, shift direction, clock polarity and phase are programmable. This allows communication with SPI-compatible devices or devices using other synchronous serial interfaces.

Features:

- Master and slave mode operation
  - Full-duplex or half-duplex operation
- Transmit and receive buffered
- Flexible data format
  - Programmable number of data bits: 2 to 8 bits
  - Programmable shift direction: LSB or MSB shift first
  - Programmable clock polarity: idle low or high state for the shift clock
  - Programmable clock/data phase: data shift with leading or trailing edge of the shift clock
- Variable baud rate
- Compatible with Serial Peripheral Interface (SPI)
- Interrupt generation
  - On a transmitter empty condition
  - On a receiver full condition
  - On an error condition (receive, phase, baud rate, transmit error)

3.18 Analog-to-Digital Converter

The XC866 includes a high-performance 10-bit Analog-to-Digital Converter (ADC) with eight multiplexed analog input channels. The ADC uses a successive approximation technique to convert the analog voltage levels from up to eight different sources. The analog input channels of the ADC are available at Port 2.

Features:

- Successive approximation
- 8-bit or 10-bit resolution
  (TUE of ± 1 LSB and ± 2 LSB, respectively)
- Eight analog channels
- Four independent result registers
- Result data protection for slow CPU access
  (wait-for-read mode)
- Single conversion mode
- Autoscan functionality
- Limit checking for conversion results
- Data reduction filter
  (accumulation of up to 2 conversion results)
- Two independent conversion request sources with programmable priority
- Selectable conversion request trigger
- Flexible interrupt generation with configurable service nodes
- Programmable sample time
- Programmable clock divider
- Cancel/restart feature for running conversions
- Integrated sample and hold circuitry
- Compensation of offset errors
- Low power modes

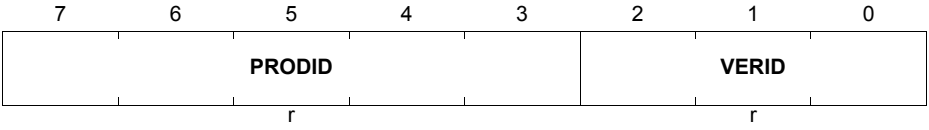
Table 31 JTAG ID Summary

ROM	XC866L-4RR	1013 9083$_H$
	XC866-4RR	1013 9083$_H$
	XC866L-2RR	1013 9083$_H$
	XC866-2RR	1013 9083$_H$

3.20 Identification Register

The XC866 identity register is located at Page 1 of address B3$_H$.

ID
Identity Register **Reset Value: 0000 0010$_B$**



Field	Bits	Type	Description
VERID	[2:0]	r	**Version ID** 010$_B$
PRODID	[7:3]	r	**Product ID** 00000$_B$

Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions Remarks
			min.	max.		
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	
Input high voltage at XTAL1	V_{IHX}	SR	0.7 × V_{DDC}	V_{DDC} + 0.5	V	
Pull-up current	I_{PU}	SR	–	-10	µA	$V_{IH,min}$
			-150	–	µA	$V_{IL,max}$
Pull-down current	I_{PD}	SR	–	10	µA	$V_{IL,max}$
			150	–	µA	$V_{IH,min}$
Input leakage current[2)]	I_{OZ1}	CC	-1	1	µA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125°C$, XC866-4FR and XC866-2FR
			-2.5	1	µA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125°C$, XC866-1FR and ROM device
Input current at XTAL1	I_{ILX}	CC	-10	10	µA	
Overload current on any pin	I_{OV}	SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma\|I_{OV}\|$	SR	–	25	mA	3)
Voltage on any pin during V_{DDP} power off	V_{PO}	SR	–	0.3	V	4)
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M	SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma\|I_M\|$	SR	–	60	mA	
Maximum current into V_{DDP}	I_{MVDDP}	SR	–	80	mA	
Maximum current out of V_{SS}	I_{MVSS}	SR	–	80	mA	

Table 34 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions Remarks
			min.	max.		
V_{DDP} = 3.3V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 8 mA
			–	0.4	V	I_{OL} = 2.5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -8 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -2.5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on $\overline{\text{RESET}}$ pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on $\overline{\text{RESET}}$ pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on Port pins	HYS	CC	0.03 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	
Input high voltage at XTAL1	V_{IHX}	SR	0.7 × V_{DDC}	V_{DDC} + 0.5	V	

Table 36 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol	Limit Values			Unit	Test Conditions/ Remarks
		min.	typ .	max.		
Switched capacitance at the analog voltage inputs	C_{AINSW} CC	–	5	7	pF	2)4)
Input resistance of the reference input	R_{AREF}CC	–	1	2	kΩ	2)
Input resistance of the selected analog channel	R_{AIN} CC	–	1	1.5	kΩ	2)

1) TUE is tested at V_{AREF} = 5.0 V, V_{AGND} = 0 V , V_{DDP} = 5.0 V.

2) Not subject to production test, verified by design/characterization.

3) This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead of this, smaller capacitances are successively switched to the reference voltage.

4) The sampling capacity of the conversion C-Network is pre-charged to V_{AREF}/2 before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than V_{AREF}/2.

4.2.4 Power Supply Current

Table 37 Power Supply Current Parameters (Operating Conditions apply; V_{DDP} = 5V range)

Parameter	Symbol	Limit Values		Unit	Test Condition Remarks
		typ.[1]	max.[2]		
V_{DDP} = 5V Range					
Active Mode	I_{DDP}	22.6	24.5	mA	[3]
Idle Mode	I_{DDP}	17.2	19.7	mA	XC866-4FR, XC866-2FR [4]
		12.5	14	mA	XC866-1FR, ROM device[4]
Active Mode with slow-down enabled	I_{DDP}	7.2	8.2	mA	XC866-4FR, XC866-2FR [5]
		5.6	7.5	mA	XC866-1FR, ROM device[5]
Idle Mode with slow-down enabled	I_{DDP}	7.1	8	mA	XC866-4FR, XC866-2FR [6]
		5.1	7.2	mA	XC866-1FR, ROM device[6]

1) The typical I_{DDP} values are periodically measured at T_A = + 25 °C and V_{DDP} = 5.0 V.

2) The maximum I_{DDP} values are measured under worst case conditions (T_A = + 125 °C and V_{DDP} = 5.5 V).

3) I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 26.7 MHz(set by on-chip oscillator of 10 MHz and NDIV in PLL_CON to 0010_B), $\overline{RESET}$ = V_{DDP}, no load on ports.

4) I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 26.7 MHz, $\overline{RESET}$ = V_{DDP} , no load on ports.

5) I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 833 KHz by setting CLKREL in CMCON to 0101_B, $\overline{RESET}$ = V_{DDP}, no load on ports.

6) I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 833 KHz by setting CLKREL in CMCON to 0101_B, $\overline{RESET}$ = V_{DDP}, no load on ports.

Table 38 Power Down Current (Operating Conditions apply; V_{DDP} = 5V range)

Parameter	Symbol	Limit Values		Unit	Test Condition Remarks
		typ.[1]	max.[2]		
V_{DDP} = 5V Range					
Power-Down Mode[3]	I_{PDP}	1	10	µA	T_A = + 25 °C.[4]
		-	30	µA	T_A = + 85 °C, XC866-4FR, XC866-2FR [4][5]
		-	35	µA	T_A = + 85 °C, XC866-1FR, ROM device[4][5]

1) The typical I_{PDP} values are measured at V_{DDP} = 5.0 V.

2) The maximum I_{PDP} values are measured at V_{DDP} = 5.5 V.

3) I_{PDP} (power-down mode) has a maximum value of 200 µA at T_A = + 125 °C.

4) I_{PDP} (power-down mode) is measured with: $\overline{\text{RESET}}$ = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subject to production test, verified by design/characterization.

4.3 AC Parameters

4.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in **Figure 38**, **Figure 39** and **Figure 40**.

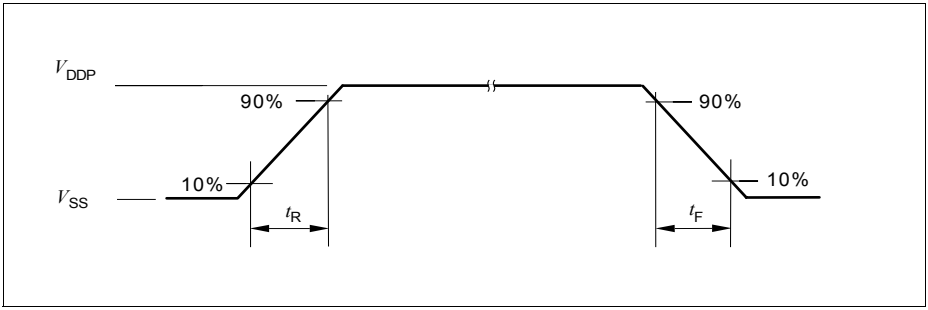


Figure 38 Rise/Fall Time Parameters

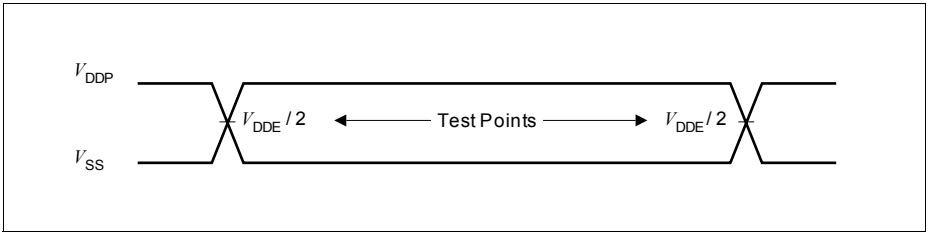


Figure 39 Testing Waveform, Output Delay

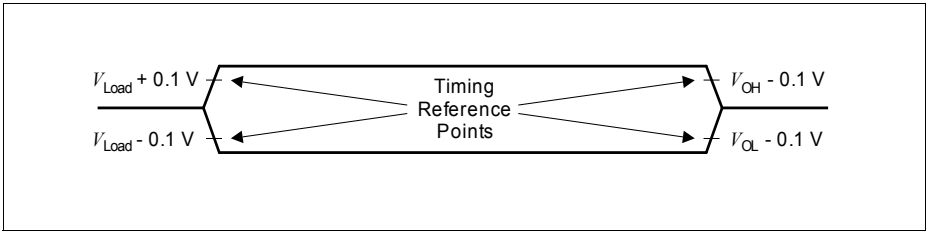


Figure 40 Testing Waveform, Output High Impedance

4.3.2 Output Rise/Fall Times

Table 41 Output Rise/Fall Times Parameters (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Conditions
		min.	max.		
V_{DDP} = 5V Range					
Rise/fall times [1] [2]	t_R, t_F	–	10	ns	20 pF. [3]
V_{DDP} = 3.3V Range					
Rise/fall times [1] [2]	t_R, t_F	–	10	ns	20 pF. [4]

[1] Rise/Fall time measurements are taken with 10% - 90% of the pad supply.

[2] Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

[3] Additional rise/fall time valid for C_L = 20pF - 100pF @ 0.125 ns/pF.

[4] Additional rise/fall time valid for C_L = 20pF - 100pF @ 0.225 ns/pF.

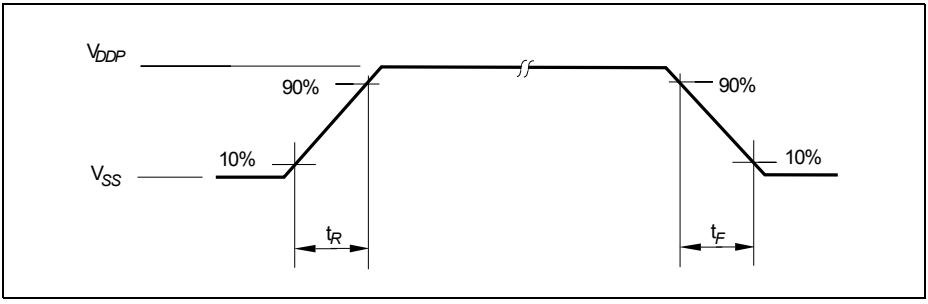


Figure 41 Rise/Fall Times Parameters

Table 45 JTAG Timing (Operating Conditions apply; C_L = 50 pF)

Parameter	Symbol		Limits		Unit
			min	max	
TMS setup to TCK ↑	t_1	SR	8.0	–	ns
TMS hold to TCK ↑	t_2	SR	5.0	–	ns
TDI setup to TCK ↑	t_1	SR	11.0	–	ns
TDI hold to TCK ↑	t_2	SR	6.0	–	ns
TDO valid output from TCK ↓	t_3	CC	–	23	ns
TDO high impedance to valid output from TCK ↓	t_4	CC	–	26	ns
TDO valid output to high impedance from TCK ↓	t_5	CC	–	18	ns

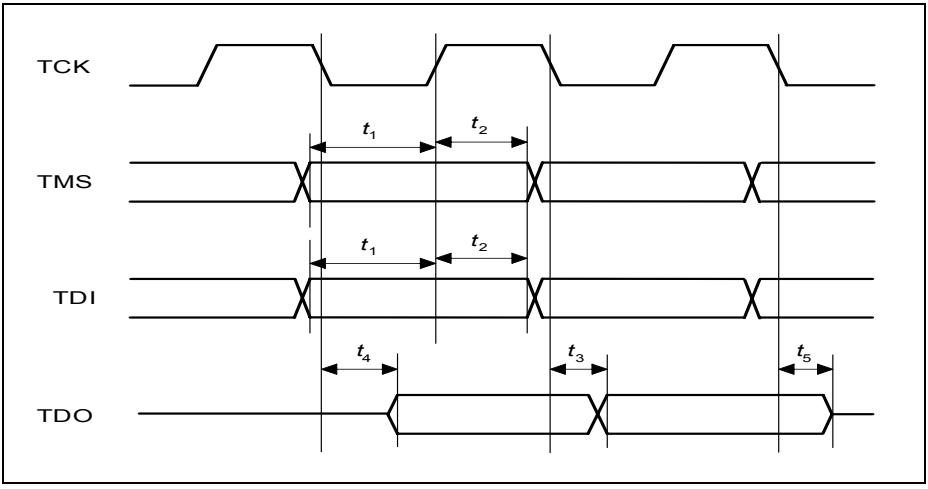


Figure 44 JTAG Timing